



GENERAL

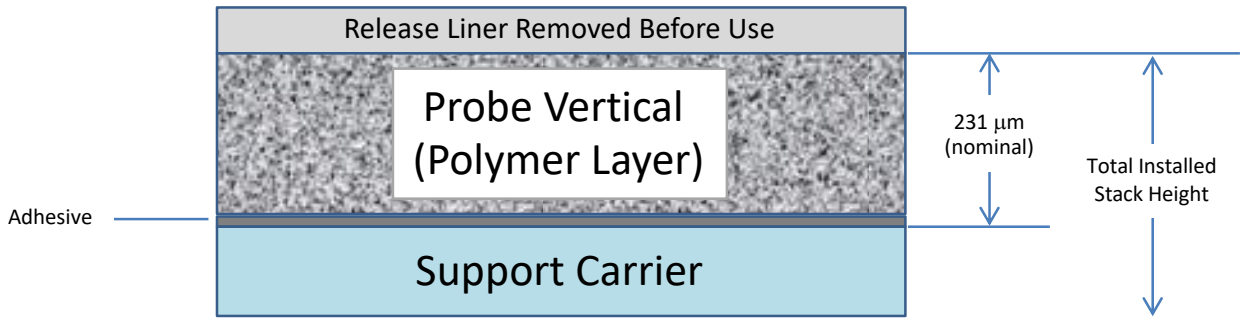
Probe Vertical® is designed to remove embedded and bonded debris from pointed probe tips and collect any loose debris that was generated during probing. The abrasive material in the polymer will remove the accumulation of embedded or bonded debris but is not so aggressive that it will alter the probe material or probe contact area.

Frequent use of the Probe Vertical®, will reduce the number of touchdowns required to remove the embedded or bonded debris probe card cleaning frequency and number of cleaning insertions varies according to the specific testing environment.

The cleaning motion with Probe Vertical® is only in the Z direction. No lateral forces are applied to the probes. The forces exerted on the probe when cleaning with Probe Vertical® are less than the forces as during normal testing operations.

The Probe Vertical® polymer layer collects and traps the debris generated during cleaning. Reuse of the cleaning pad will cause the trapped debris to be pushed deeper into the polymer. This allows reuse of the same location several times. Visually check the pad from time to time to ensure that it does not become overloaded with debris, which will reduce the cleaning efficiency of the material. To achieve maximum cleaning efficiency, offset each touchdown location approximately 2X the probe diameter in the XY directions, such that probe tip always touches the clean surface of the cleaning material.

CROSS SECTION



	Cleaning Material Configuration			
	Sheet	200mm Wafer	300mm Wafer	Custom Install
Polymer Layer Thickness	231 µm (nominal)	231 µm (nominal)	231 µm (nominal)	231 µm (nominal)
Support Carrier	143 µm (PET nominal)	725 ± 20µm (SEMI Standard)	775 ± 20µm (SEMI Standard)	Contact ITS
Total Installed Stack Height	374 ± 20µm	956 ± 30µm	1006 ± 30 µm	Contact ITS

PROBE VERTICAL®

PCC PD-PV001

